


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company	 STMicroelectronics International N.V
1.2 PCN No.	AMS/23/14070
1.3 Title of PCN	Bumping Process Change
1.4 Product Category	See product list
1.5 Issue date	2023-09-20

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	KRISZTINA NEMETH
2.1.2 Phone	+49 89460062210
2.1.3 Email	krisztina.nemeth@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Marcello SAN BIAGIO
2.1.2 Marketing Manager	Salvatore DI VINCENZO
2.1.3 Quality Manager	Jean-Marc BUGNARD

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Wafer fabrication	ASE Taiwan

4. Description of change

	Old	New
4.1 Description	Printing Bumping Process (ASE, Taiwan)	Plating Bumping Process (SCS =Stats Chippac Singapore)
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No impact on the Electrical, Mechanical, Quality and Reliability Characteristics.	

5. Reason / motivation for change

5.1 Motivation	Following ASE communication about the termination of the current Printing Bumping Process, ST plans to qualify and implement a New Bumping Process in SCS (Stats Chippac Singapore) OSAT. No change to the Package Outline Assembly (mechanical) and electrical characteristics (datasheet). No other change is made with respect to this PCN. Wafer diffusion as well as Testing & Finishing/ DPS remain unchanged both in terms of flow and location.
5.2 Customer Benefit	SERVICE CONTINUITY

6. Marking of parts / traceability of change

6.1 Description	The traceability of the new parts will be ensured by physical Die Level and Lot Level codification.
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7. Timing / schedule

7.1 Date of qualification results	2023-08-28
7.2 Intended start of delivery	2023-11-30
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	14070 ReliabilityEvaluationReport-V788_V1.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2023-09-20

9. Attachments (additional documentations)

14070 Public product.pdf
14070 ReliabilityEvaluationReport-V788_V1.pdf

10. Affected parts

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STC3115AIJT	
	STC3115IJT	
	LD39115J33R	
	STBB2J30-R	
	STBB2JAD-R	

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